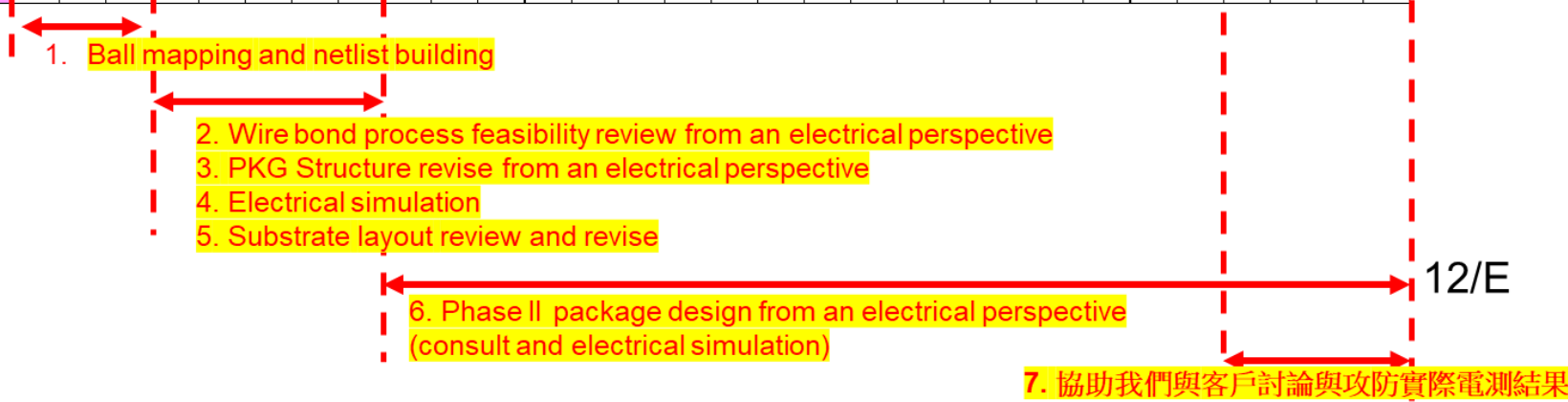
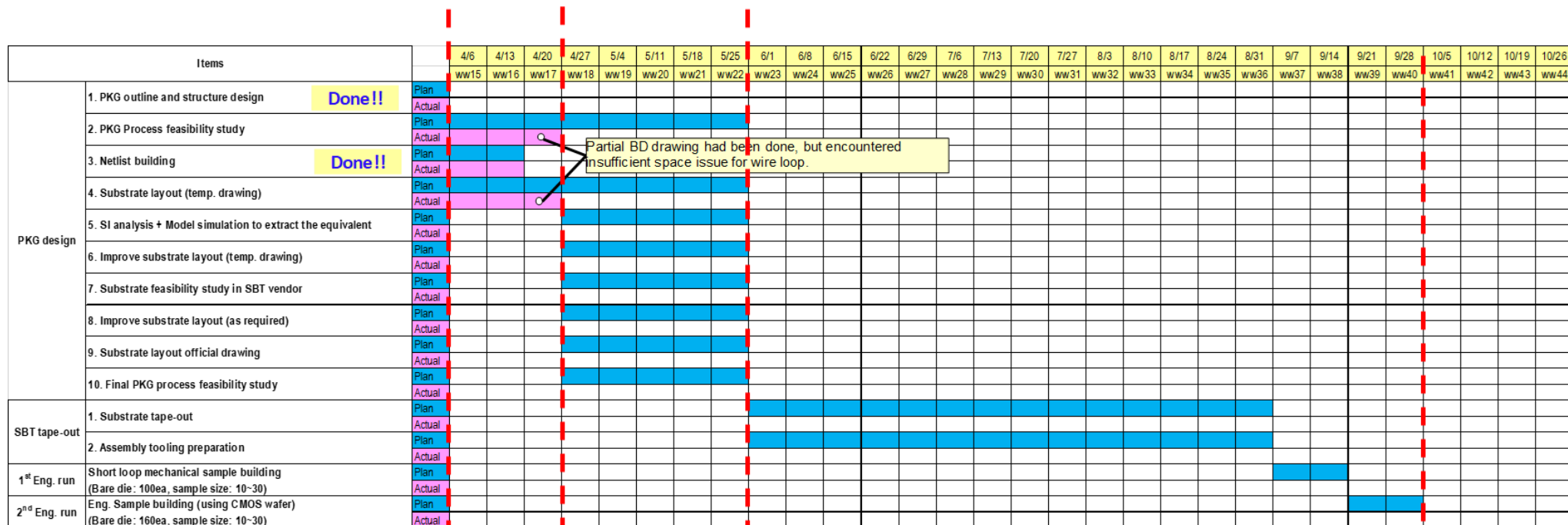


# 須交付項目：

<b>Package design</b>	<b>1. PKG outline and structure design</b>
	<b>2. PKG Process feasibility study</b>
	<b>3. Netlist building</b>
	<b>4. Substrate layout (temp. drawing)</b>
	<b>5. SI analysis + Model simulation to extract the equivalent</b>
	<b>6. Improve substrate layout (temp. drawing)</b>
	<b>7. Substrate feasibility study in SBT vendor</b>
	<b>8. Improve substrate layout (as required)</b>
	<b>9. Substrate layout official drawing</b>
	<b>10. Final PKG process feasibility study</b>

# 須配合之服務時程：



12/E